I claim:

1. A termination coating for use with a surface mount component comprising a thermoplastic or thermoset resin and an electrically conductive filler.
2. The termination coating of claim 1, wherein the surface mount component is a multilayer ceramic capacitor.
3. The termination coating of claim 2, wherein the electrically conductive filler is selected from the group consisting of copper flake, copper powder, silver plated copper, nickel, silver plated nickel, cobalt, cobalt nickel alloy, indium or mixtures thereof.
4. The termination coating of claim 3, wherein the electrically conductive filler is selected from the group consisting of copper flake, copper powder or a mixture thereof.
5. The termination coating of claim 2, wherein the multilayer ceramic capacitor is a base metal multilayer ceramic capacitor.
6. The termination coating of claim 1, wherein the resin is selected from the group consisting of epoxy resin, phenoxy resin, phenolic resin, acrylics, urethanes, vinyls, cyanate esters, bismaleimides, butadienes, esters, butadiene-acrylonitrile, benzoxazines, oxetanes, siliconès, silanes, siloxanes, novolacs, cresols, ethersulphones, phenylene oxides, imides, fluoropolymers, episulfides, cyanovinylether, oxazoline, oxazine, propargylether or mixtures thereof.
7. The termination coating of claim 4, wherein at least a portion of the copper flake, copper powder or mixture thereof is coated with an organic material.
8. The termination coating of claim 7, wherein the organic material is fatty acid.

9. The termination coating of claim 1, further comprising one of more of the group consisting of catalysts, solvents, hardener, thixotropic agents, fillers, flowing agents, leveling agents, anticratering agents, defoaming agents, anti-settling agents and corrosion inhibitors.

10. The termination coating of claim 1, wherein the coating comprises in the range of about 3 to about 25 weight percent of the resin.

11. The termination coating of claim 10, wherein the coating comprises in the range of about 5 to about 15 weight percent of the resin.

12. The termination coating of claim 1, wherein the coating comprises in the range of about 30 to about 90 weight percent of the conductive filler.

13. The termination coating of claim 12, wherein the coating comprises in the range of about 40 to about 80 weight percent of the conductive filler.

14. The termination coating of claim 9, wherein the coating comprises in the range of about 0.1 to about 10 weight percent hardener.

15. The termination coating of claim 14, wherein the coating comprises in the range of about 1 to about 5 weight percent hardener.

16. The termination coating of claim 9, wherein the coating comprises in the range of about 0.5 to about 7 weight percent thixotropic agent.

17. The termination coating of claim 9, wherein the coating comprises in the range of about 0.01 to about 1 weight percent catalyst.

18. A base metal multilayer ceramic capacitor having the coating of claim 1.

19. The termination coating of claim 1, wherein the coating may be cured at a temperature less than about 300°C.

20. The termination coating of claim 1, wherein the coating may be cured at a temperature less than about 230°C.

21. A method of providing a stress absorbing layer on a metal-glass termination comprising the step of coating a metal-glass termination with the termination coating of claim 1.

22. A method for providing a coating on at least a portion of one or more multilayer capacitors comprising the steps of:

forming a liquid termination coating comprising one or more thermoplastic or thermoset resins and a conductive filler,

applying the termination coating to at least a portion of the multilayer capacitor; and

curing the capacitor and coating so that the coating dries to form a solid coating on the capacitor.

23. The method of claim 22, wherein the termination coating is applied via dipping the multilayer capacitor into the coating.

24. The method of claim 22, wherein the capacitor and coating are cured in an inert atmosphere.

25. The method of claim 22, wherein the coating is in the range of about 5 to about 100 microns thick.

26. The method of claim 22, wherein the capacitor and coating are cured at a temperature less than about 300°C.

27. The method of claim 26, wherein the capacitor and coating are cured at a temperature less than about 250°C.

28. The method of claim 15, wherein the capacitor and coating are cured at a temperature less than about 230°C.

29. The method of claim 15, wherein the conductive filler is copper powder, copper flake or a mixture thereof.